

# SOT933-1

plastic low profile fine-pitch ball grid array package; 180 balls; body 12 x 12 x 1 mm

8 February 2016

Package information

## 1. Package summary

|                                |                                                |
|--------------------------------|------------------------------------------------|
| Terminal position code         | B (bottom)                                     |
| Package type descriptive code  | LFBGA180                                       |
| Package type industry code     | LFBGA180                                       |
| Package style descriptive code | LFBGA (low profile fine-pitch ball grid array) |
| Package style suffix code      | NA (not applicable)                            |
| Package body material type     | P (plastic)                                    |
| JEDEC package outline code     | MO-205                                         |
| Mounting method type           | S (surface mount)                              |
| Issue date                     | 23-1-2006                                      |

Table 1. Package summary

| Symbol         | Parameter                      |  | Min   | Typ | Nom | Max  | Unit |
|----------------|--------------------------------|--|-------|-----|-----|------|------|
| D              | package length                 |  | 11.9  | -   | 12  | 12.1 | mm   |
| E              | package width                  |  | 11.9  | -   | 12  | 12.1 | mm   |
| A              | seated height                  |  | [tbd] | -   | 1.5 | 1.5  | mm   |
| A <sub>2</sub> | package height                 |  | 0.95  | -   | 1   | 1.1  | mm   |
| n <sub>2</sub> | actual quantity of termination |  | -     | -   | 180 | -    |      |



2. Package outline

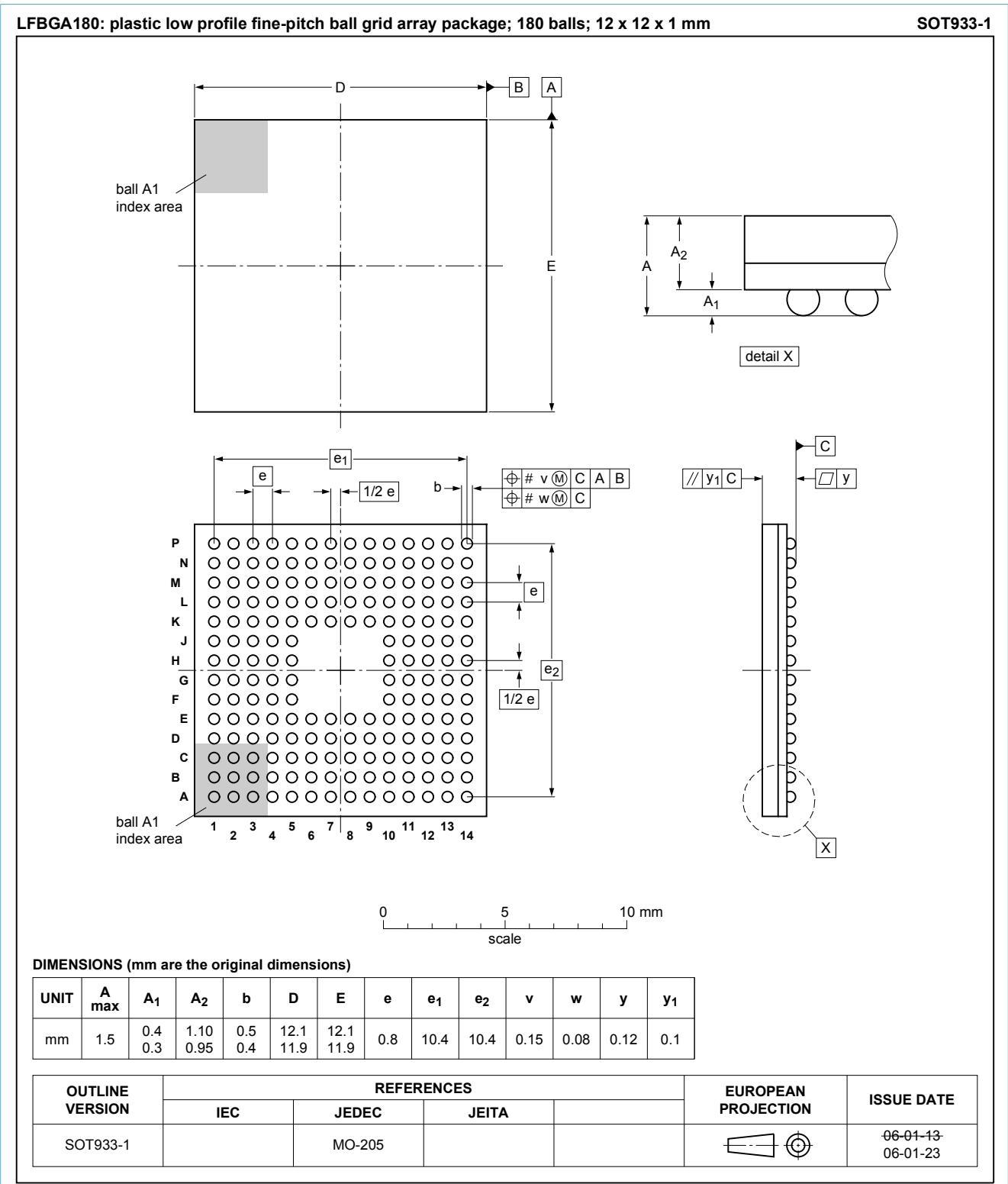


Fig. 1. Package outline LFBGA180 (SOT933-1)

### 3. Legal information

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Date of release: 8 February 2016